AMENDMENTS TO THE CLAIMS:

The following listing of claims replaces all prior listings, and all prior versions, of claims in the application.

LISTING OF CLAIMS:

1. (Currently amended) An electronic device comprising an IC element, and a first circuit layer and a second circuit layer,

wherein the IC element further provides a base substrate formed of silicon, a semiconductor circuit layer forming a semiconductor circuit on one side of the base substrate, an electrode formed on the semiconductor circuit layer, and the other side of the base substrate does not have any electrode formed thereon,

wherein the first circuit layer is electrically connected either to the other side of the base substrate or the electrode, and the second circuit layer is electrically connected to that same other side of the base substrate or the electrode, whichever remains unconnected to the first circuit layer, and

wherein ~~any of~~ the other side of the base substrate and the electrode are~~is~~ connected either to the first circuit layer or the second circuit layer, respectively, via a conductive adhesive agent or an anisotropic conductive adhesive agent.

2. (Cancelled).

3. (Previously presented) The electronic device according to claim 1 wherein the conductive adhesive agent is comprised of a thermal hardenable matrix resin, and metallic pieces of granular form, scalelike form or acicular form.

4. (Cancelled).

5. (Previously presented) The electronic device according to claim 1 wherein the anisotropic conductive adhesive layer includes a matrix resin and conductive particles comprised of either metallic particles or organic resinous particles having a metallic layer formed on the surface thereof.

6. (Previously presented) The electronic device according to claim 1 wherein the IC element is sealed by a matrix resin of anisotropic conductive adhesive agent.

7. (Previously presented) The electronic device according to claim 1 wherein at least either the first or the second circuit layers includes a conductive layer of aluminum or copper.

8. (Previously presented) The electronic device according to claim 1 wherein at least either the first or the second circuit layers is supported on a base substrate comprised of an organic resin, this organic resin being selected from the group consisting of polyvinyl chloride (PVC), acrylonitrile butadiene styrene (ABS), polyethylene terephthalate (PET), polyethylene terephthalate glycol (PETG), polyethylene naphthalate (PEN), polycarbonate resin (PC), biaxial polyester (O-PET), or polyimide resin.

9. (Previously presented) The electronic device according to claim 1 wherein at least either the first or the second circuit layers is supported on a base substrate comprised of paper.

10. (Previously presented) The electronic device according to claim 5 wherein the IC element is sealed by a matrix resin of anisotropic conductive adhesive agent.

11. (Previously presented) The electronic device according to claim 10 wherein at least either the first or the second circuit layers includes a conductive layer of aluminum or copper.

12. (Previously presented) The electronic device according to claim 11 wherein at least either the first or the second circuit layers is supported on a base substrate comprised of an organic resin, this organic resin being selected from the group consisting of polyvinyl chloride (PVC), acrylonitrile butadiene styrene (ABS), polyethylene terephthalate (PET), polyethylene terephthalate glycol (PETG), polyethylene naphthalate (PEN), polycarbonate resin (PC), biaxial polyester (O-PET), or polyimide resin.

13. (Previously presented) The electronic device according to claim 12 wherein at least either the first or the second circuit layers is supported on a base substrate comprised of paper.

14. (Previously presented) The electronic device according to claim 1, wherein at least one of the first and second circuit layers is a transmission and reception antenna.

15. (Previously presented) The electronic device according to claim 1, wherein the first circuit layer includes a slit and operates as a transmission and reception antenna, and the second circuit layer is a bridging plate electrically connecting the IC element and the first circuit layer.